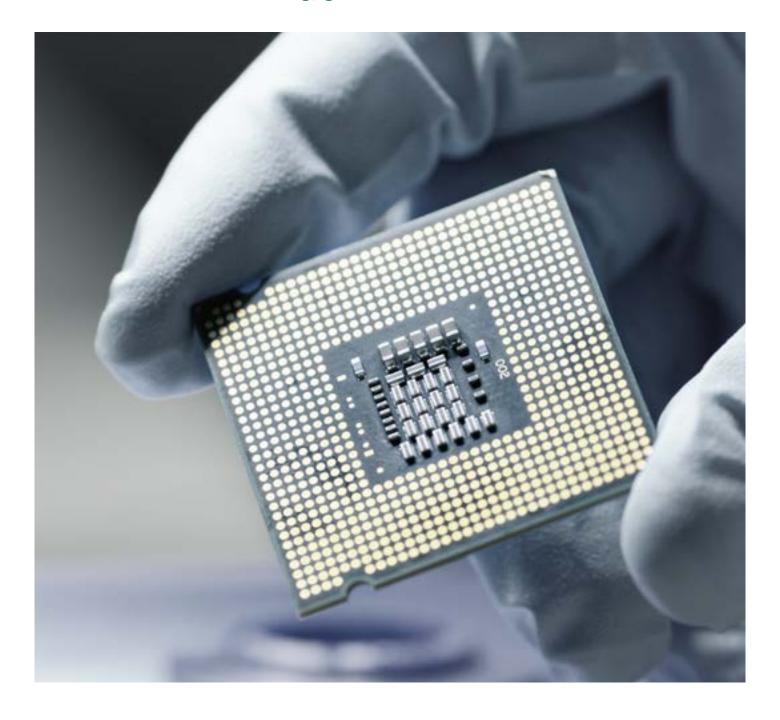


Semiconductor manufacturing solutions

Quick connectors for cooling, gas and vacuum lines





Solutions enabling efficient and modular semiconductor manufacturing

Thanks to Staubli connector solutions, the installation, operations and maintenance of semicon manufacturing equipment is QUICK, EASY, CLEAN & SAFE

- · No matter the connection media (water, glycol-water, coolant, gas, vacuum)
- · No matter the conditions and environnement (temperature, pressure, flow, cleanliness requirements,...)

Main benefits



No leakage



Adapted to both low and high temperature



Compatible with fluids used in semicon manufacturing industry



Quick to connect & disconnect



Ergonomic easy to connect/disconnect



High flow rates



Compact design



No equipment contamination

Low pressure drop

quaranteed



Reliable



Local support at every stage of customer's project

Connection solutions for each step of semicon manufacturing process:

Wafer manufacturing, Front-end, Wafer test & Back-end

Guaranteeing efficient and clean cooling, gas & vacuum supply connections between:

Equipment

Sub-equipment

Components

Utilities

WAFER MANUFACTURING

FRONT END

WAFER TEST

- Single cristal growth
- Lapping/polishing CMP
- Deposition
- Litography
- Etching
- Implant/anneal
- Cleaning
- Metrology/ inspection

Probing

- Dicing
- Bonding molding
- Final test

Mono couplings

MCB



Characteristics:

non-spill, automatic lock

Material: stainless steel

Temperature (°C): -80 to +250

Max pressure (bar): 100

Nominal diameters (mm): 3, 5, 8, 12, 16

HCB



Characteristics: non-spill, bayonette

Material: stainless steel

Temperature (°C): -40 to +250

Max pressure (bar): 350

Nominal diameters (mm): 3, 5, 8, 12,

16, 20

DAG



Characteristics:

non-spill, automatic lock

Material: stainless steel

Temperature (°C): -30 to +150

Max pressure (bar): 16

Nominal diameters (mm): 3, 6, 9

CBI



Characteristics:

non-spill, automatic lock

Material: brass

Temperature (°C): -20 to +250

Max pressure (bar): 16

Nominal diameters (mm): 3, 6, 9, 12,

Rackable couplings

CGD/L



Characteristics: non-spill, blind-mate. misalignement compensation

Material: aluminium

Temperature (°C): -40 to +175

Max pressure (bar): 16

Nominal diameters (mm): 3, 5, 8, 12

DDG



Characteristics: non-spill, blind mate, misalignement compensation

Material: stainless steel

Temperature (°C): -20 to +150

Nominal diameters (mm): 3, 6, 15

Max pressure (bar): 16



All products performances values are depending on the application, type of media and size of product.

Large bore couplings

TDU



Characteristics: full-flow

Material: stainless steel

Temperature (°C): -10 to +80

Max pressure (bar): 10

Nominal diameters (mm): 24, 50

Multi couplings

MUI TI



- Connecting multiple circuits, different media and electric lines at once.
- Customized design.

For additional information, more solutions and options, please conact your local Staubli representative

Semiconductor manufacturing solutions 3



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